



Rear I/O



Features

- High-performance Intel® 9th/8th Gen Core™ processors
- Intel® OpenVINO validated
- Supports three independent display outputs
- 4x RJ45 Gigabit Ethernet port (2x Supports 802.3at PoE+)
- Flexible PCI-E / PCI expansion slot
- 3x M.2 (B-Key/E-Key/M-Key)
- Over/Under/Reverse voltage protection

Specifications

System Mainboard	MB230AF with Intel® Q370 PCH
CPU Type	9th/8th Gen Intel® Core™ i7/i5/i3 desktop processors
System Speed	Up to 4.00 GHz
Memory	2x DDR4-2666/2400 SO-DIMM, Max. 32GB
Front Panel External I/O	1x RS232/422/485 port for COM#1~COM#2 3x RS232 ports for COM#3~COM#4 2x RS232 ports for COM#5~6 from optional IP214/5 1x DisplayPort (1.2) 2x RJ45 Gigabit Ethernet port (Supports 802.3at PoE+) 1x 5-pins DC-in terminal block type for 12V (±10%) or 18V (-10%)~24V (+10%) 2x Antenna holes 1x expansion slot
Rear Panel External I/O	1x DVI-D + HDMI(1.4) 4x USB3.1 ports 2x Antenna holes 2x RJ45 Gigabit Ethernet port + Dual USB3.1 stack ports 1x Red HDD LED 1x power button with Green LED indicator 1x 2-pin terminal block 2x SIM Card
Expansion Slots	1x Flexible PCI-E / PCI expansion slot 1x M.2 (B-Key supports USB2.0 for 4G/LTE) 1x M.2 (E-Key supports PCI-E + USB2.0 for CNVi)
Storage	2x 2.5" HDD/SSD 1x M.2 (M-Key supports PCI-E(4x) + SATA for NVMe SSD)
Construction	Aluminum & steel
Chassis Color	Silver & Gray
Mounting	Desktop & wall mount
Dimensions	210mm (W) x 285mm (D) x 109mm (H) 8.27" (W) x 11.22" (D) x 4.29" (H)
Weight	4.5 kg

Operating Temperature	-20°C to 70°C (-4°F~158°F) (for 35W CPU)
Storage Temperature	-20°C~80°C (-4°F~176°F)
Relative Humidity	5~90% @60°C, (non-condensing)
Vibration	Operating : 3Grms / 5~500Hz
Shock	Operating : 20G / 11ms Non-operating : 40G / 11ms
Certification	CE / FCC Class A/ LVD

Dimensions and Drawing

